Transilvania University of Braşov, Romania

Study program: Electronic and Communication Integrated Systems

Faculty: Electrical Engineering and Computer Science

Study period: 2 years (master)

Academic year structure: 2 semesters (14 weeks per semester) Examination sessions (two): winter session (January/February)

summer session (June/July)

Courses per years (C= course; S = seminar; L = laboratory; P = project)

1st Year

No.	Course	Code	1 Semester					2 nd Semester					
crt.		Code	C	S	L	Р	Cred	С	S	L	Р	Cred	
01	Software technologies for systems testing	SECI101	1	-	-	2	6						
02	Distributed and real-time systems	SECI102	2	-	-	2	6						
03	Packet processors	SECI103	2	-	-	-	6						
04	Data communications	SECI104	1	-	2	1	6						
05	Ethics and academic integrity	SECI105	1	-	-	-	4						
06	Research (practice)	SECI106	-	-	-	-	2						
Thoro	Thoroughgoing Study Direction: Digital communication networks												
07	Digital signal processors	SECI207						2	-	-	1	6	
08	Industrial control and data transmission networks	SECI208						1	-	-	2	6	
09	Quality of Services and computer networks security	SECI209						1	-	-	2	6	
10	Research (practice)	SECI210						-	-	-	_	2	
	One discipline is ch	osen from	each	pack	age								
Option	nal package no. 1												
11	Communication networks modelling	SECI211						1			1	4	
' '	Protocols for interconnecting hybrid networks	SECI212						-	_	-	1	4	
Option	nal package no. 2												
12	Physical layer of communication networks and switching techniques	SECI213						2	-	-	1	6	
	Smart antennas for mobile communications systems	SECI214											
Thoro	ughgoing Study Direction: Embedded systems	•											
13	Research (practice)	SECI215						-	-	-	_	2	
One discipline is chosen from each package													
Option	nal package no. 1												
14	Modern architectures of processors and microcontrollers	SECI216						1	_	_	2	6	
'-	Hardware Description Languages	SECI217						Ċ			_		
Option	nal package no. 2	1							ı				
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15	Analog interfacing and conditioning systems	SECI218					1			2	6
15	Network on Chip	SECI219					1	-	ı	2	0
Option	Optional package no. 3										
	Industrial control and data transmission	SECI220 SECI221					1				
16	networks							_	-	1	5
	VLSI testing technologies and reliability										
Option	Optional package no. 4										
	Interfacing standards for embedded systems	SECI222					2				
17	Systems on chip security	SECI223						-	-	1	5
	Programmable logic systems	SECI224									
Option	Optional package no. 5										
10	Microcontroller and DSP programming	SECI225					7			1	_
18	Neural networks	SECI226					2	_	-		6

2nd Year

Thorough 1 Inte 2 Mo 3 Res Optional p	elligent communication networks bile communications and mobile computing search (practice) One discipline is chos	SECI301 SECI302 SECI303	1 2	S	_ _	Р	Cred	С	S	L	Р	Cred				
1 Inte 2 Mo 3 Res Optional p	elligent communication networks bile communications and mobile computing search (practice) One discipline is chos	SECI301 SECI302 SECI303	1	-												
2 Mo 3 Res Optional p	bile communications and mobile computing search (practice) One discipline is cho	SECI302 SECI303		-			Thoroughgoing Study Direction: Digital communication networks									
3 Res	search (practice) One discipline is chos	SECI303	2		_	2	5									
Optional p	One discipline is cho	L		-	1	1	7									
4 Dis			-	-	-	-	6									
4 Dis	nackage no 1	One discipline is chosen from each package														
4 	package no. 1															
4 _{Dac}	tributed databases for telecommunications	SECI304	1		1	1	6									
nac	dio channel modelling	SECI305	1	-	1	1	6									
Optional p	Optional package no. 2															
Des	sign and testing of digital communication	SECI306			1											
5 net	works	3EC1306	2	-		1	6									
Mu	Itimedia streams in IP networks	SECI307														
Thorough	Thoroughgoing Study Direction: Embedded systems															
6 Res	search (practice)	SECI308	-	-	-	-	6									
One discipline is chosen from each package																
Optional p	package no. 1															
7 Sys	stems remote control	SECI309	1		1	1	6									
/ Virt	tual instrumentation in embedded systems	SECI310		_		ļ	O .									
Optional p	package no. 2															
Ind	ustrial and consumer microcontroller-based	SECI311		-												
8 арр	plications	3ECI3 I I	1		-	2	6									
ASI	IC design	SECI312														
Optional p	package no. 3															
Lov	w-power intelligent sensor networks	SECI313														
9 Ene	ergy management of embedded electronics and	SECI314	2	-	1	1	6									
con	nmunications systems	JECIJ 14														
Optional p	package no. 4															
App	plications in telecommunications, domotics and	SECI315														
10 me	dical electronics	JECIJ IJ	2		-	2	6									
Aut	tomotive control systems	SECI316	۷	-	-	_	Б									
Cor	mputer-aided design in electronics EDA	SECI317														

All directions												
11	Research Projects Management	SECI401	1	ı	ı	1	4					
12	Research (practice)	SECI402	-	-	-	1	10					
13	Practice for master thesis preparing	SECI403	-	-	-	1	10					
14	Preparing the master thesis	SECI404	-	-	-	1	6					